PRELIMINARY AMENDMENT

Serial Number: Unknown Filing Date: Herewith

Title: ELECTRONIC ASSEMBLIES WITH HIGH CAPACITY HEAT SINKS

Assignee: Intel Corporation

REMARKS

Page 7

Dkt: 884.867US3 (Intel)

This application is a divisional of application U.S. Serial No. 09/950,100, filed on September 10, 2001. The parent application was subject to a restriction requirement dated July 29, 2002. In that application, Applicants elected to prosecute claims that were directed to embodiments of the inventive subject matter shown in FIGS. 5-10.

In the present application, Applicants elect to prosecute claims that are directed to embodiments of the inventive subject matter shown in FIGS. 11-17, 19-20, and 23.

By way of this amendment, dependent claims 23 and 29 have been amended, as discussed below. The amendments to the claims are made to satisfy Applicants' preferences, not necessarily to satisfy any legal requirement(s) of the patent laws, and they are not intended to limit the scope of equivalents to which any claim element may be entitled.

Relationship of Claims 1-30 to Claims of Parent Application

Claim 1 of this divisional application is identical to original claim 1 of parent application U.S. Serial No. 09/950,100.

Claim 2 of the present application is identical to original claim 3 of the parent application.

Claim 3 of the present application is identical to original claim 4 of the parent application.

Claim 4 of the present application is identical to original claim 5 of the parent application.

Claim 5 of the present application is identical to original claim 3 of the parent application.

Claim 6 of the present application is identical to original claim 4 of the parent application.

Claim 7 of the present application is identical to original claim 11 of the parent application.

Title: ELECTRONIC ASSEMBLIES WITH HIGH CAPACITY HEAT SINKS

Assignee: Intel Corporation

Page 8

Dkt: 884.867US3 (Intel)

Claim 8 of the present application is identical to original claim 12 of the parent application.

Claim 9 of the present application is identical to original claim 3 of the parent application.

Claim 10 of the present application is identical to original claim 4 of the parent application.

Claim 11 of the present application is identical to original claim 14 of the parent application.

Claim 12 of the present application is identical to original claim 15 of the parent application.

Claim 13 of the present application is identical to original claim 16 of the parent application.

Claim 14 of the present application is identical to original claim 17 of the parent application.

Claim 15 of the present application is identical to original claim 18 of the parent application, except that "system" has been substituted for "assembly".

Claim 16 of the present application is identical to original claim 19 of the parent application, except that "system" has been substituted for "assembly".

Claim 17 of the present application is identical to original claim 20 of the parent application, except that "system" has been substituted for "assembly".

Claim 18 of the present application is identical to original claim 21 of the parent application, except that "system" has been substituted for "assembly".

Claim 19 of the present application is identical to allowed claim 1 of the parent application, except that the phrase "wherein an upper portion of each of the fins is bent in the same relative direction" has been substituted for the phrase "the fins are curved in the same relative direction".

Claim 20 of the present application is identical to allowed claim 48 of the parent application.

Serial Number: Unknown Filing Date: Herewith

Title: ELECTRONIC ASSEMBLIES WITH HIGH CAPACITY HEAT SINKS

Assignee: Intel Corporation

application.

Claim 21 of the present application is identical to allowed claim 49 of the parent

Claim 22 of the present application is identical to allowed claim 50 of the parent application.

Claim 23 of the present application is similar to allowed claim 14 of the parent application. Claim 23 has been amended by substituting the phrase "is to comprise" for "comprise".

Claim 24 of the present application is similar to allowed claim 15 of the parent application.

Claim 25 of the present application is identical to allowed claim 1 of the parent application, except that the phrase "wherein an upper portion of each of the fins is bent" has been added.

Claim 26 of the present application is identical to allowed claim 48 of the parent application.

Claim 27 of the present application is identical to allowed claim 49 of the parent application.

Claim 28 of the present application is identical to allowed claim 50 of the parent application.

Claim 29 of the present application is similar to allowed claim 14 of the parent application. Claim 29 has been amended by substituting the phrase "is to comprise" for "comprise".

Claim 30 of the present application is similar to allowed claim 15 of the parent application.

Serial Number: Unknown Filing Date: Herewith

Title: ELECTRONIC ASSEMBLIES WITH HIGH CAPACITY HEAT SINKS

Assignee: Intel Corporation

Conclusion

Consideration of claims 1-30 is respectfully requested. The Examiner is invited to telephone Applicants' attorney Walter W. Nielsen (located in Phoenix, Arizona) at 602-298-8920 or the below-signed attorney (located in Minneapolis, Minnesota) to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

DANIEL P. CARTER ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. Attorneys for Intel Corporation P.O. Box 2938
Minneapolis, Minnesota 55402
612-349-9592

Λ

Page 10

Dkt: 884.867US3 (Intel)

Date:	Nov. 19 2003	By:	ann M. McCeach		
	,		Ann M. McCrackin		
			Reg. No. 42,858		
CERTIFIC	CATE UNDER 37 CFR § 1.8: The undersign	ed hereb	y certifies that this correspondence is being deposited with the	United States Po	

Name	KACIA	LEE	Signature	Kacia Lee	